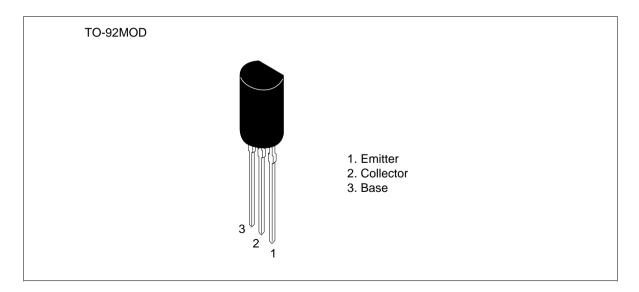
Silicon NPN Epitaxial

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Application

- Low frequency high voltage amplifier
- Complementary pair with 2SB715, 2SB716 and 2SB716A

Outline





Absolute Maximum Ratings (Ta = 25°C)

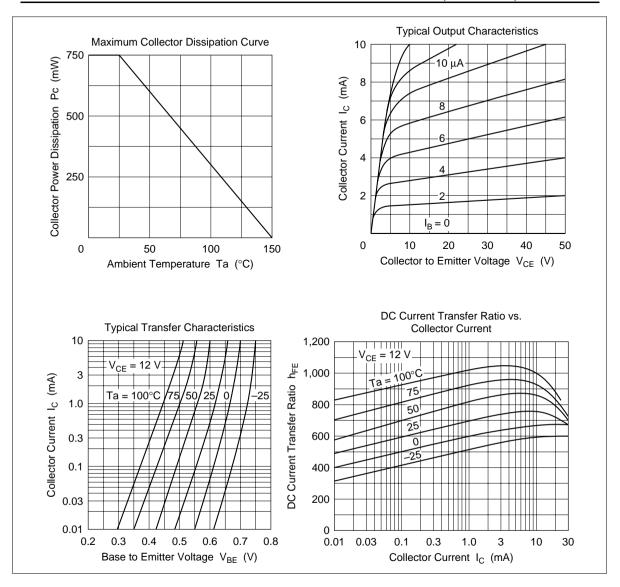
Item	Symbol	2SD755	2SD756	2SD756A	Unit
Collector to base voltage	V_{CBO}	100	120	140	V
Collector to emitter voltage	V _{CEO}	100	120	140	V
Emitter to base voltage	V _{EBO}	5	5	5	V
Collector current	I _c	50	50	50	mA
Collector power dissipation	P_c	750	750	750	mW
Junction temperature	Tj	150	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	-55 to +150	°C

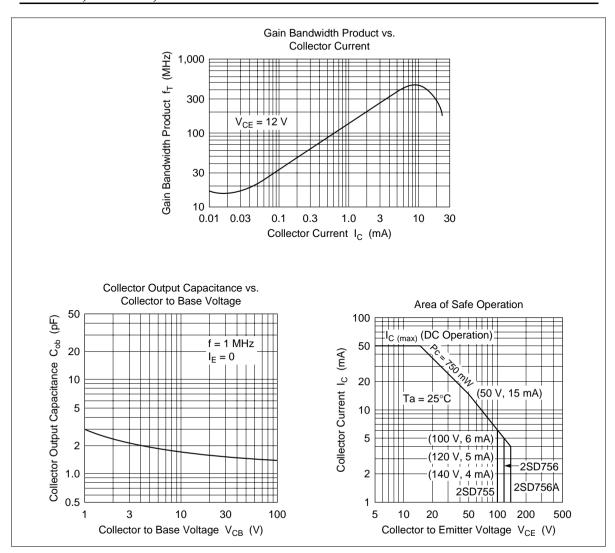
Electrical Characteristics (Ta = 25°C)

		2SD755 2SD756			2SD756A							
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	100	_	_	120	_	_	140	_	_	V	$I_C = 1 \text{ mA},$ $R_{BE} = \infty$
Collector to base breakdown voltage	$V_{(BR)CBO}$	100	_	_	120	_	-	140	_	-	V	$I_{C} = 10 \ \mu\text{A}, \ I_{E} = 0$
Collector cutoff current	I _{CBO}	_	_	0.5	_	_	0.5	_	_	0.5	μΑ	V _{CB} = 100 V, I _E = 0
DC current transfer ratio	h _{FE1} *1	250	_	1200	250	_	800	250	_	500		$V_{CE} = 12 \text{ V},$ $I_{C} = 2 \text{ mA}$
	h _{FE2}	125	_	_	125	_	_	125	_	-		$V_{CE} = 12 \text{ V},$ $I_{C} = 10 \text{ mA}$
Base to emitter voltage	V_{BE}	_	_	0.75	_		0.75	_	_	0.75	V	$V_{CE} = 12 \text{ V},$ $I_{C} = 2 \text{ mA}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	0.2	_	_	0.2	_	_	0.2	V	$I_C = 10 \text{ mA},$ $I_B = 1 \text{ mA}$
Gain bandwidth product	f _T		350		_	350	_	_	350		MHz	V _{CE} = 12 V, I _C = 5 mA
Collector output capacitance	Cob	_	1.6	_	_	1.6	_	_	1.6	_	pF	$V_{CB} = 25 \text{ V}, I_{E} = 0,$ f = 1 MHz

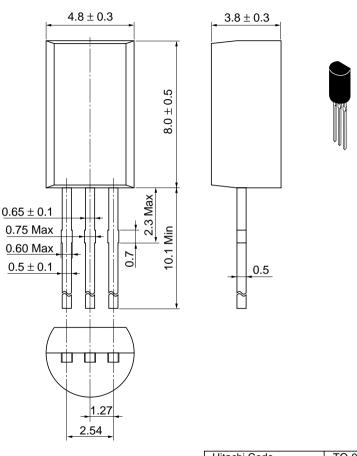
Note: 1. The 2SD755, 2SD756 and 2SD756A are grouped by $h_{\mbox{\scriptsize FE1}}$ as follows.

	D	E	F
2SD755	250 to 500	400 to 800	600 to 1200
2SD756	250 to 500	400 to 800	_
2SD756A	250 to 500	_	_





Unit: mm



Hitachi Code TO-92 Mod

JEDEC —

EIAJ Conforms

Weight (reference value) 0.35 g

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